

ABSTRACT

The present invention provides a contact assembly, a chuck, and an electroplating apparatus, and relates to the field of semiconductor electroplating technology. The contact assembly extends along a linear path, and comprises a mounting body and a contact body. The mounting body includes a plurality of mounting portions arranged at intervals, the plurality of mounting portions are distributed along the length direction of the mounting body, the adjacent mounting portions are separated by a first hollow area, and each mounting portion is provided with a guide portion protruding from the mounting body. The contact body is provided with a plurality of second hollow areas distributed at intervals along the length direction, and the contact body is connected to the mounting body for contacting a substrate. The contact assembly provided by the present invention has a higher material utilization rate, produces less waste, and yields a higher output rate, reducing the processing cost. In addition, the contact assembly exhibits superior bending performance, making it easier for the contact assembly to be bent into a ring shape for use from a state of extending along a linear path.